

**REMARKS**

Claims 1-24 are pending. Claims 6 and 17 have been amended. Applicant reserves the right to pursue the original claims and other claims in this and in other applications.

The specification is objected to. Reconsideration is requested. The title has been amended as required.

Claims 6-7 and 17 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite. Claims 6 and 17 have been amended to obviate the rejection.

Claims 1-19 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,326,936 ("Taniuchi"). Reconsideration is requested.

In a preferred embodiment, the printed circuit board 40 carrying an electronic component 10 is connected to a circuit pattern formed on a base substrate 1. A metal plate 4 is soldered upon a land 2 via a solder layer 5. The land 2 is formed with through-holes 6, the through-holes providing electrical interconnection to a rear side land, as explained in more detail in the specification, pages 20+. The claimed invention should not be limited, however, to the preferred embodiments described and shown in the specification and drawings.

Claim 1 says there is "a land formed on a front surface of [a] base substrate and a metal plate soldered upon [the] land via a solder layer." This is an important feature of the invention. The Taniuchi device does not have a land. The Office Action cites to element 1a as the land but element 1a is a through-hole. Even if the wall of the through-hole 1a, not described except in col. 3, lines 39 and 54-55; col. 4, line 24, but shown in Figures 2A-2B

and 3A-3C, is a land, the solder ring 7 of the printed circuit board 1 is not a layer but solder that fills the space between the pin 3a and the wall of the through-hole 1a. Calling solder ring 7 a layer does not make it so. For this reason, claim 1 should be allowable over Taniuchi.

Claims 2-24 either depend from claim 1 or contain similar limitations as claim 1. Therefore, claims 2-24 should be allowable over Taniuchi for at least the same reasons as claim 1.

In view of the above, Applicant believes the pending application is in condition for allowance.

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Respectfully submitted,

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